

FEATURES

- Rx Mixer with Integrated Fractional-N PLL**
- RF Input Frequency Range: 1200 MHz to 3600 MHz**
- Internal LO Range: 2500 MHz to 2900 MHz**
- Input P1dB: +12dBm**
- Input IP3: +27dBm**
- IP3 Optimization via External Pin**
- SSB Noise Figure: 14dB**
- Voltage Conversion Gain: 6dB**
- Matched 200Ω IF Output Impedance**
- IF 3dB Bandwidth: 500MHz**
- Programmable via Three Wire SPI Interface**
- 40 Pin 6mm x 6mm LFCSP Package**

APPLICATIONS

Cellular Base Stations

GENERAL DESCRIPTION

The ADRF6604 is a high dynamic range active mixer with integrated PLL and VCO. The PLL/Synthesizer uses a Fractional-N PLL to generate a F_{LO} input to the mixer. The reference input can be divided or multiplied then applied to the PLL phase detector. The PLL can support input reference frequencies between 12MHz and 160MHz. The phase detector output controls a charge pump whose output is integrated in an off-chip loop-filter. The loop filter output is then applied to an integrated VCO. The VCO output at $2 * F_{LO}$ is then applied to a LO divider as well as to a programmable PLL divider.

Part #	Internal LO Range	+/-3dB RF In Balun Range	+/-1dB RF In Balun Range
ADRF6601	750 MHz	300 MHz	450 MHz
	1160 MHz	2500 MHz	1600 MHz
ADRF6602	1550 MHz	1000 MHz	1350 MHz
	2150 MHz	3100 MHz	2750 MHz
ADRF6603	2100 MHz	1100 MHz	1450 MHz
	2600 MHz	3200 MHz	2850 MHz
ADRF6604	2500 MHz	1200 MHz	1600 MHz
	2900 MHz	3600 MHz	3200 MHz

The programmable divider is controlled by a sigma-delta modulator (SDM). The modulus of the SDM can be programmed between 2 and 2047.

The active mixer converts the single-ended 50Ω RF input to a 200 Ω differential IF output. The IF output can operate up to 500 MHz.

The ADRF6604 is fabricated using an advanced silicon-germanium BiCMOS process. It is available in a 40-lead, exposed-paddle, Pb-free, 6mm x 6mm LFCSP package. Performance is specified over a -40°C to +85°C temperature range.

FUNCTIONAL BLOCK DIAGRAM

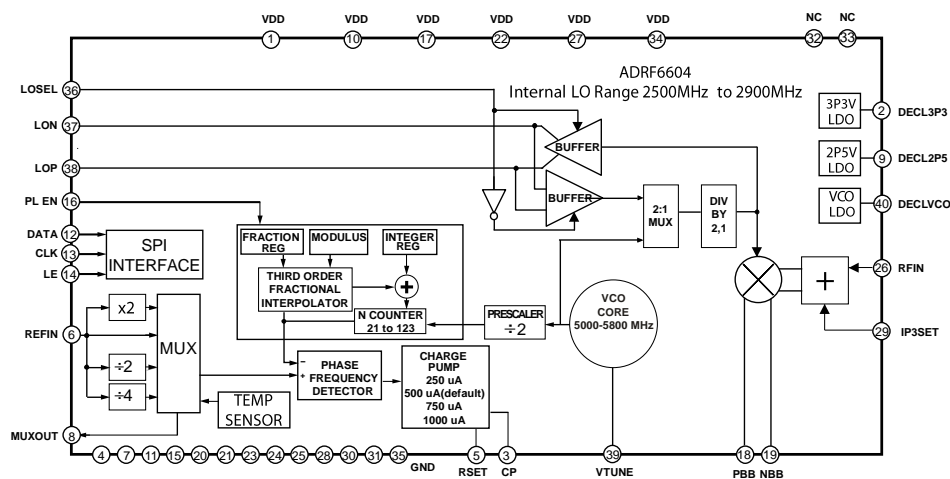


Figure 1. ADRF6604 Block Diagram

Rev. PrD

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REVISION HISTORY

6/09 Rev B, created from Rev A using ADI Template

6/09 Rev C, updated LO In, RF out, and VCO frequencies, updated register information, updated block diagrams. Added spec for RF Input Frequency range and for LO to IF leakage.

8/09 Rev D, updated to keep consistent with rev 0 Outline, updated registers per latest information, added main body text

SPECIFICATIONS

$V_S = 5V$; Ambient Temperature (T_A) = 25°C; $F_{REF} = 76.8MHz$; $F_{IF} = 153MHz$; $F_{RF} = 2600MHz$ unless otherwise noted

Table 1.

Parameter	Conditions	Min	Typ	Max	Unit
Frequency Range		2500		2900	
RF Input Frequency Range	+/-3dB	300		2500	
RF INPUT @2400MHz					
Input return loss	Relative to 50Ω (can be improved with external match)		12		dB
Input P1dB			12		dBm
Second Order Intercept (IIP2)	-6dBm Each Tone		55		dBm
Third Order Intercept (IIP3)	-6dBm Each Tone		27		dBm
Noise Figure	Single Side Band		14		dB
	With a -4dBm Interferer 5MHz Away		TBD		dB
IF/2 Spurious (2x2 IMD product)	IF = 150MHz		TBD		dBc
LO to RF Leakage	At 1x LO Frequency, 50Ω Termination at the RF Port		-35		dBm
RF INPUT @2600MHz					
Input return loss	Relative to 50Ω (can be improved with external match)		12		dB
Input P1dB			12		dBm
Second Order Intercept (IIP2)	-6dBm Each Tone		55		dBm
Third Order Intercept (IIP3)	-6dBm Each Tone		27		dBm
Single Side Band Noise Figure			14		dB
	With a -4dBm Interferer 5MHz Away		TBD		dB
IF/2 Spurious (2x2 IMD product)	IF = 150MHz		TBD		dBc
LO to RF Leakage	At 1x LO Frequency, 50Ω Termination at the RF Port		-35		dBm
IF OUTPUT					
Voltage Conversion Gain	200Ω Load		TBD		dB
IF Bandwidth	Small Signal 3dB Bandwidth		500		MHz
	1V p-p Signal 3dB Bandwidth		TBD		MHz
Output Common Mode Voltage	External Pull-up Balun or Inductors Required		5		V
Group Delay Flatness	Any 5MHZ/50MHz		TBD		ns p-p
Gain Flatness	Over RF Frequency Range, any 5MHZ/50MHz		0.2/1.0		dB
Gain Flatness	Over Frequency Range, any 5MHZ/50MHz		0.2/1.0		dB
Gain Variation	Over Full Temp Range		1.0		dB
Output Swing	Differential 200Ω Load		2		V p-p
Output Return Loss	Relative to 200Ω		TBD		dB
LO to IF Leakage			TBD		dB
LO INPUT/OUTPUT					
Frequency Range	LOP, LON Externally Applied LO Input	250		6000	MHz
Output Level (LO as Output)	1x LO into a 50Ω Load, LO Output Buffer Enabled		TBD		dBm
Input Level (LO as Input)			0		dBm
Input Impedance	Externally Applied 1x LO, Internal PLL Disabled		50		50Ω

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Parameter	Conditions	Min	Typ	Max	Unit
SYNTHESIZER SPECIFICATIONS					
Frequency Range	Synthesizer Specifications Referenced to 1x LO Internally Generated LO	2500		2900	MHz
Figure of Merit			TBD		dBc/Hz
Spurs					
Fractional Spurs	Offset from Integer LO SDM Modulus = 1536, $F_{PFD} = 38.4$ MHz)				
	100kHz		-54		dBc
	200kHz		-60		dBc
	400kHz		-66		dBc
	800kHz		-70		dBc
Reference Spurs	$F_{REF} = 76.8MHz$				
	$F_{REF}/2$		-80		dBc
	F_{REF}		-80		dBc
	$>F_{REF}$		TBD		dBc
PHASE NOISE					
	Frequency = 2500 to 2900 MHz, PFD Frequency= 30.72 MHz or 38.4 MHz				
	@ 1 kHz to 10 kHz offset		-85		dBc/Hz
	@ 100 kHz offset		-103		dBc/Hz
	@ 500 kHz offset		-123		dBc/Hz
	@ 1 MHz offset		-130		dBc/Hz
	@ 5 MHz offset		-143		dBc/Hz
	@ 10 MHz offset		-150		dBc/Hz
	@ 20 MHz offset		-156		dBc/Hz
Integrated Phase Noise	1 KHz to 10 MHz integration bandwidth		0.75		°rms
Frequency Settling			1.0		ms
Phase Detector Frequency	Min/Max		24/40		MHz
REFERENCE CHARACTERISTICS					
REFIN Input Frequency	REFIN, REFOUT		12/160		MHz
REFIN Input Capacitance	Min/Max			4	pF
REFIN Input Current				±100	µA
REFOUT Output Swing	Load ≤ 5 pF (REFIN = 76.8 MHz), Load ≤ 10 pF (REFIN = 38.4 MHz)	0.25		2.7	V
REFOUT Duty Cycle		45		55	%
CHARGE PUMP					
Pump Current	Programmable to 250uA, 500uA, 750uA, 1000uA		500		µA
Output Compliance Range		1		2.8	Volts

SPECIFICATIONS

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Parameter	Conditions	Min	Typ	Max	Unit
LOGIC INPUTS	CLK, DATA, LE				
V_{INH} Input High Voltage		1.4		3.3	V
V_{INL} Input Low Voltage		0		0.7	V
I_{INH}/I_{INL} Input Current			±TBD		μA
C_{IN} Input Capacitance			TBD		pF
POWER SUPPLIES	Pins VCC, VCCbb, VCCrf				
Voltage Range	VCC, VCCbb, VCCrf	4.75	5	5.25	V
Supply Current	PLL only		85		mA
	Normal Mode (Internal PLL Disabled)		150		mA
	Calibration Mode (Internal PLL Enabled)		240		mA
	Power Down Mode		TBD		uA

TIMING CHARACTERISTICS¹

$V_{DD} = 5\text{ V} \pm 5\%$;

Table 2.

Parameter	Limit	Unit	Test Conditions/Comments
t_1	20	ns min	LE Setup Time
t_2	10	ns min	DATA to CLOCK Setup Time
t_3	10	ns min	DATA to CLOCK Hold Time
t_4	25	ns min	CLOCK High Duration
t_5	25	ns min	CLOCK Low Duration
t_6	10	ns min	CLOCK to LE Setup Time
t_7	20	ns min	LE Pulse Width

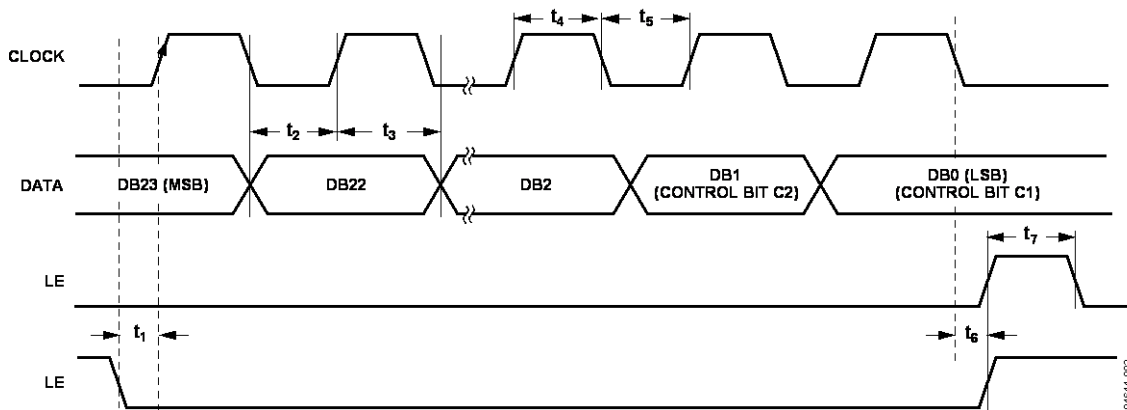


Figure 2. Timing Diagram

04644-002

ABSOLUTE MAXIMUM RATINGS

Table 3. ADRF6604 Absolute Maximum Ratings

Parameter	Rating
Supply Voltage VCC, VCCbb, VCCrf	-0.5 to 6 V
Digital I/O CLK, DATA, LE	-0.3 to 3.3 V
IHI, ILO, QHI, QLO, RFIP	TBD V
θ_{JA} (Exposed Paddle Soldered Down)	TBD °C/W
Maximum Junction Temperature	125°C
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

θ_{JA} is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 4. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
40 Lead LFCSP_VQ	TBD	TBD	°C/W

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

FUNCTIONAL BLOCK DIAGRAM

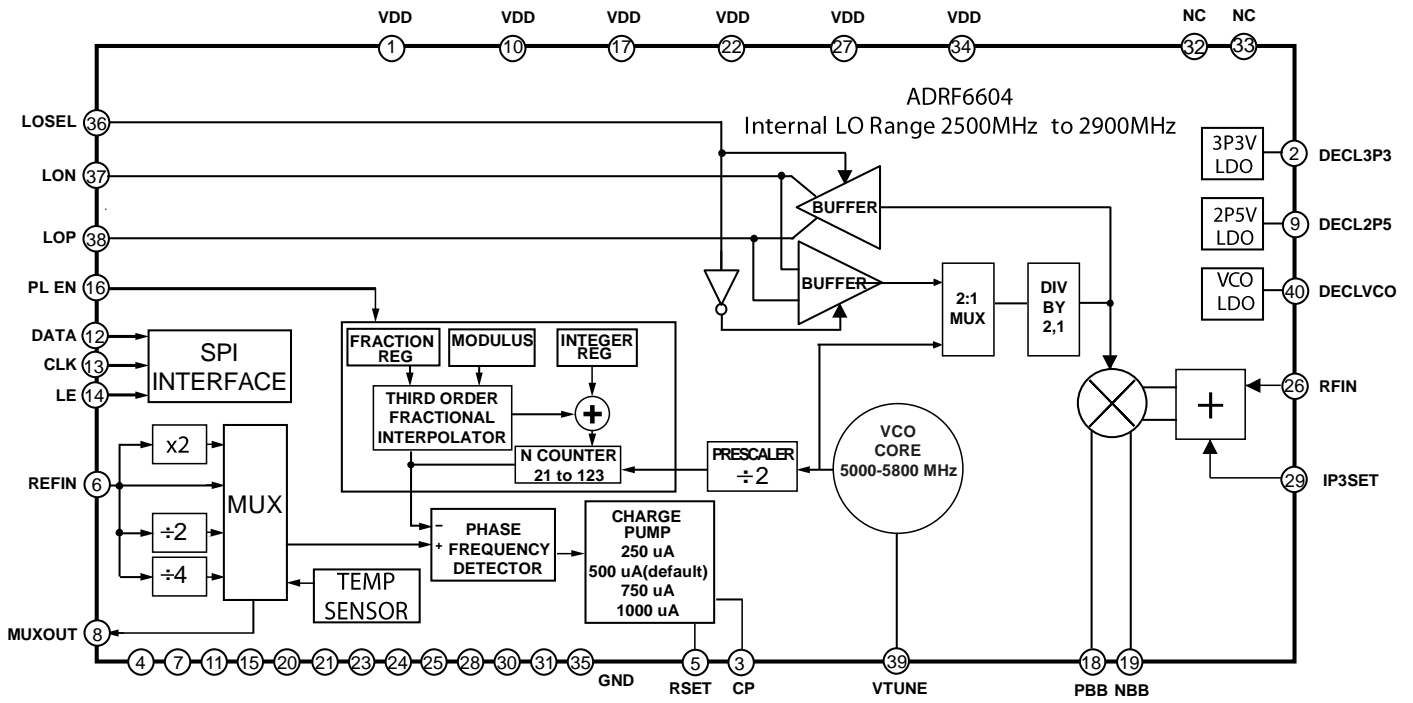


Figure 3. ADRF6604 Functional Block Diagram

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

Table 5. ADRF6604 Pin Function Descriptions

Pin No.	Mnemonic	Description
Pin Nr.	Mnemonic	Description
1,10,17, 22,27,34	VCC, VCClo, VCCbb, VCCrf	Power Supply: Power supply voltage range is 4.75 V to 5.25 V. Each pin should be decoupled with a 100 pF and 0.1 μF capacitors located close to the pin.
2	DECL3P3	Decoupling Nodes for 3.3V LDO: Connect a 0.1 μF capacitor between this pin and ground.
3	CP	Charge Pump: Chargepump Output Pin. Connect to V _{TUNE} through loop filter
4,7,11,15, 20,21,23, 24,25,28, 30,31,35	GND	Ground: Connect these pins to a low impedance ground plane.
5	R _{SET}	<p>Charge Pump Current: The nominal charge pump current can be set to either 250 μA, 500 μA, 750 μA or 1 mA using DB10 and DB11 of Register 4 and by setting DB18 to 0 (Internal Reference Current). In this mode, no external R_{SET} is required. If DB18 is set to 1, the four nominal charge pump currents (I_{NOMINAL}) can be externally tweaked according to the equation.</p> $R_{SET} = \left[\frac{217.4 \times I_{CP}}{I_{NOMINAL}} \right] - 37.8[\Omega]$
6	REF _{IN}	Reference Input: Nominal input level is 1V _{pp} . Input range is 12 MHz to 160 MHz.
8	MUXOUT	Multiplexer Output: This output can be programmed to provide the Reference Output signal or the Lock Detect signal. The output is selected by programming the appropriate register.
9	DECL2P5	Decoupling Nodes for 2.5V LDO: Connect a 0.1 μF capacitor between this pin and ground.
12	DATA	Serial Data Input: The serial data input is loaded MSB first with the three LSBs being the control bits.
13	CLK	Serial Clock Input: This serial clock input is used to clock in the serial data to the registers. The data is latched into the 24-bit shift register on the CLK rising edge. Maximum clock frequency is 20 MHz.
14	LE	Load Enable: When the LE input pin goes high, the data stored in the shift registers is loaded into one of the six registers, the relevant latch being selected by the first three control bits of the 24-bit word.
16	PLL_EN	PLL Enable: Switch between Internal PLL and External LO Input. When this pin is logic high the mixer LO is automatically switched to the internal PLL and the internal PLL is powered up. When this pin is logic low the internal PLL is powered down and the external LO input is routed to the mixer LO inputs. The SPI may alternatively be used to switch modes.
18,19	PBB, NBB	Mixer IF Outputs: Should be pulled to VCC with RF Chokes
26	RF _{IN}	RF Input: Single-ended, 50 Ω RF Input.
29	IP3Set	IP3Set: Connect resistor to VCC to adjust IP3 : Nominally leave open
33,32	NC	No Connection
36	LODRV_EN	<p>LO Driver Enable: Together with Pin 16 (PLL_EN), this digital input pin determines whether the LOP and LON pins operate as inputs or outputs, as shown in the next section. LOP and LON become inputs if the PLL_EN pin is low or if the PLL_EN pin is set high with PLEN bit (DB6) Register 5 set to low. LOP and LON become outputs if either the LODRV_EN pin or LDRV bit (DB3) of Register 5 is set high while the PLL_EN pin is set high. External LO drive frequency must be 1xLO.</p> <p>This pin should not be left floating.</p>
37,38	LON, LOP	Local Oscillator Input/Output: The internally generated 1XLO is available on these pins. When internal LO generation is disabled, an external 1XLO can be applied to these pins.
39	VTUNE	VCO Control Voltage Input: This pin is driven by the output of the loop filter. Nominal input voltage range on this pin is 1.5 V to 2.5 V
40	DECLVCO	Decoupling Nodes for VCO LDO: Connect a 100 pF and a 10 μF capacitor between this pin and ground.
	EP	Exposed Paddle: The exposed paddle should be soldered to a low impedance ground plane.

TYPICAL PERFORMANCE CHARACTERISTICS

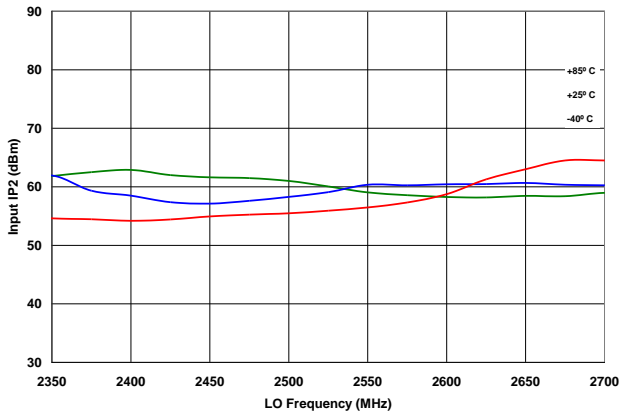


Figure 4. ADRF6604 IIP2 vs. LO Frequency, Internally Generated LO, RF In = -10dBm, IF Out = 139/140MHz

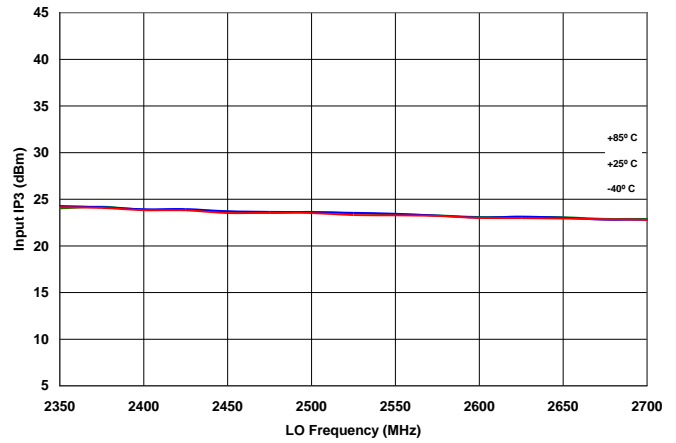


Figure 5. ADRF6604 IIP3 vs. LO Frequency, Internally Generated LO, RF In = -10dBm, IF Out = 139/140MHz, IP3SET pin open, CAPDAC not optimized

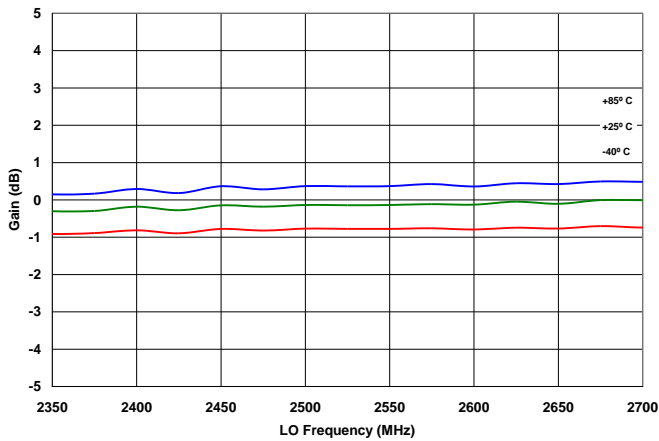


Figure 6. ADRF6604 Gain vs. LO Frequency, Internally Generated LO, RF In = -10dBm, IF Out = 139/140MHz

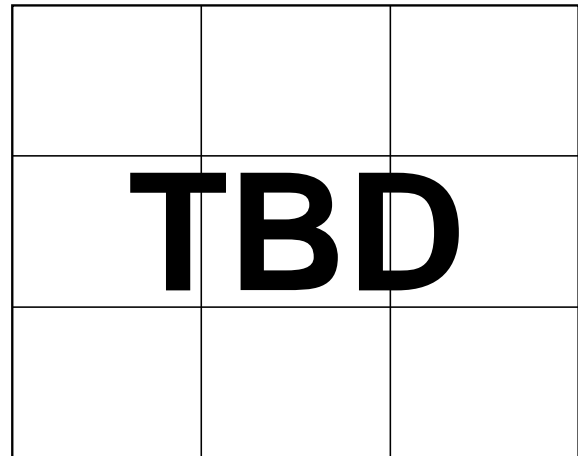


Figure 7. . ADRF6604 Integrated and Spot Phase Noise vs. LO Frequency, Internally Generated LO, RF In = -10dBm, IF Out = 139/140MHz

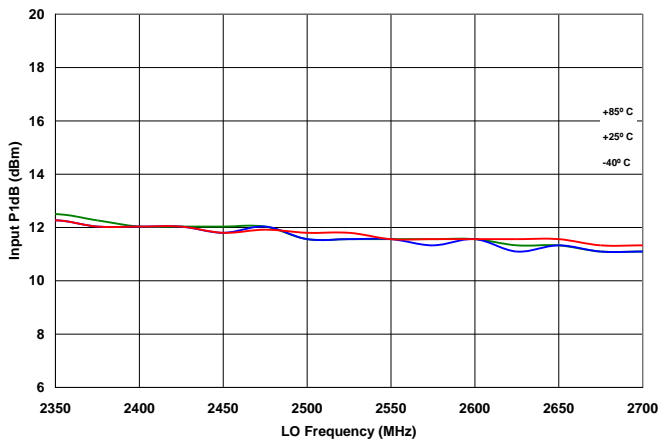


Figure 8. ADRF6604 P1dB vs. LO Frequency, Internally Generated LO, RF In = -10dBm, IF Out = 139/140MHz

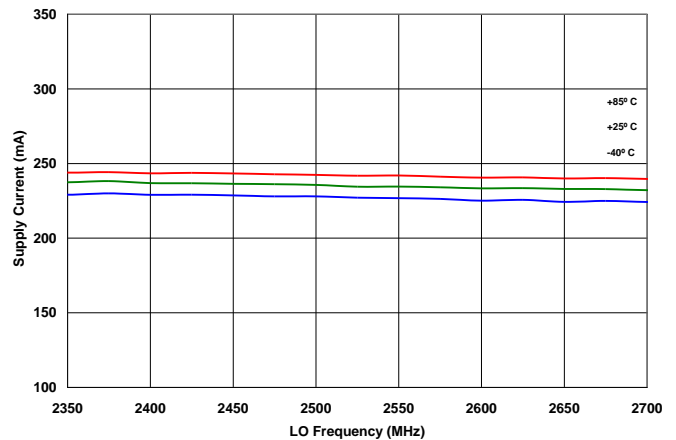


Figure 9. . ADRF6604 Supply Current vs. LO Frequency, Internally Generated LO, RF In = -10dBm, IF Out = 139/140MHz

REGISTER STRUCTURE

Table 6. Register Maps for ADRF6601. The three LSBs determine which register is programmed

REGISTER 0 – INTEGER DIVIDE CONTROL (default: 0x0001C0)

												DIVIDE MODE	INTEGER DIVIDE RATIO							CONTROL BITS			
DB23	DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	0	0	0	0	0	0	DM	ID6	ID5	ID4	ID3	ID2	ID1	ID0	C3(0)	C2(0)	C1(0)

DM	DIVIDE MODE
0	FRACTIONAL (DEFAULT)
1	INTEGER

ID6	ID5	ID4	ID3	ID2	ID1	ID0	Divide Ratio
0	0	1	0	1	0	1	21 (Integer mode only)
0	0	1	0	1	1	0	22 (Integer mode only)
0	0	1	0	1	1	1	23 (Integer mode only)
0	0	1	1	0	0	0	24
-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-
0	1	1	1	0	0	0	56 (default)
-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-
1	1	1	0	1	1	1	119
1	1	1	1	0	0	0	120 (Integer mode only)
1	1	1	1	0	0	1	121 (Integer mode only)
1	1	1	1	0	1	0	122 (Integer mode only)
1	1	1	1	0	1	1	123 (Integer mode only)

REGISTER 1 – MODULUS DIVIDE CONTROL (default: 0x003001)

										MODULUS DIVIDE RATIO										CONTROL BITS			
DB23	DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	0	0	0	MD10	MD9	MD8	MD7	MD6	MD5	MD4	MD3	MD2	MD1	MD0	C3(0)	C2(0)	C1(1)

MD10	MD9	MD8	MD7	MD6	MD5	MD4	MD3	MD2	MD1	MD0	Modulus
0	0	0	0	0	0	0	0	0	0	1	1
0	0	0	0	0	0	0	0	0	0	1	0
-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-
0	0	0	0	1	1	0	0	0	0	0	1536 (default)
-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-
1	1	1	1	1	1	1	1	1	1	1	2047

REGISTER 2 – FRACTIONAL DIVIDE CONTROL (default: 0x001802)

										FRACTIONAL DIVIDE RATIO										CONTROL BITS			
DB23	DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	0	0	0	0	FD10	FD9	FD8	FD7	FD6	FD5	FD4	FD3	FD2	FD1	FD0	C3(0)	C2(1)	C1(0)

FD10	FD9	FD8	FD7	FD6	FD5	FD4	FD3	FD2	FD1	FD0	Fractional Value
0	0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	1	1
-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-
0	1	1	0	0	0	0	0	0	0	0	768 (default)
-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-
Fractional Value must be less than Modulus											<MDR

REGISTER 3 – SIGMA DELTA MODULATOR DITHER CONTROL (default: 0x10000B)

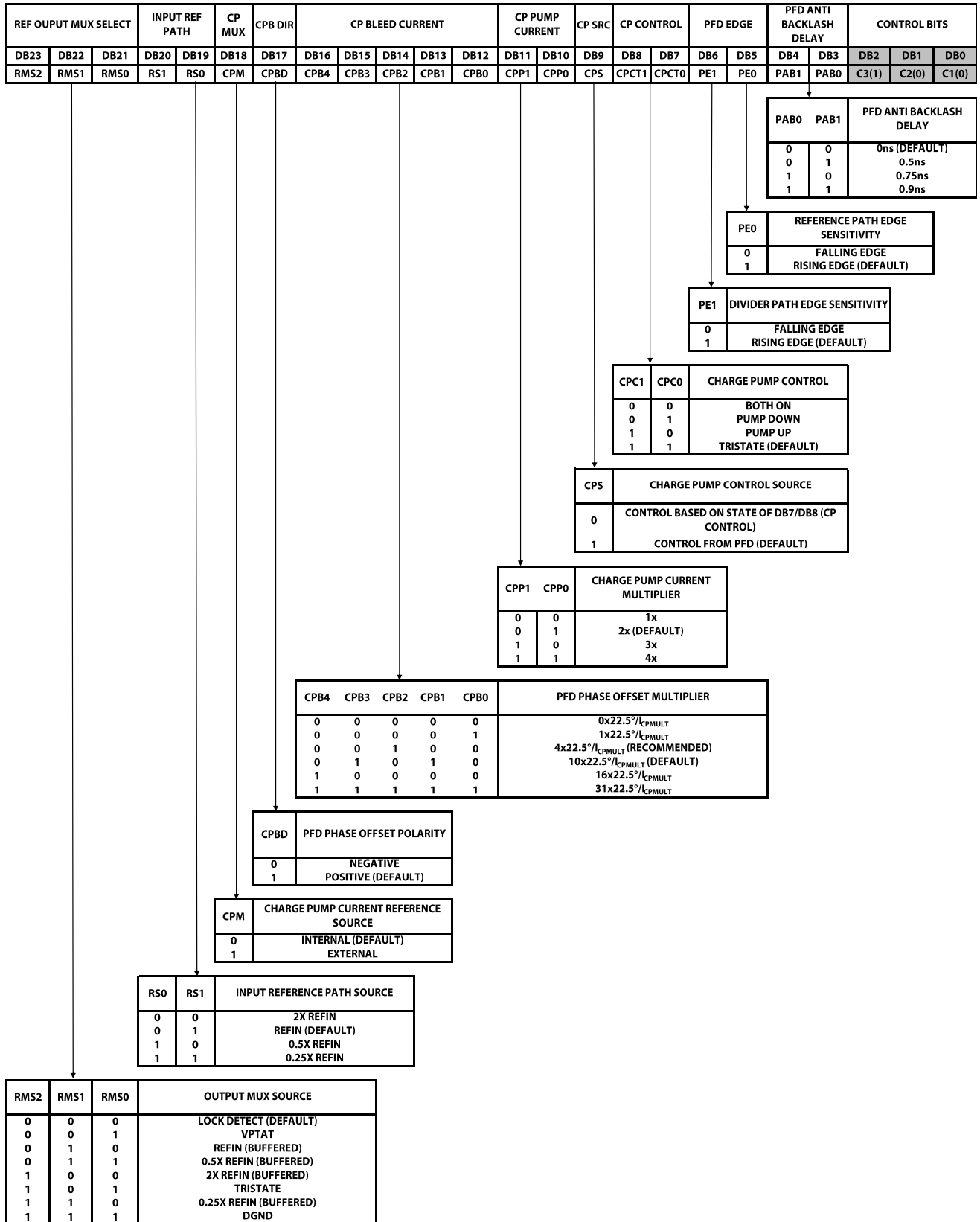
Dither Magnitude		Dither Enable	Dither Restart Value																Control Bits				
DB23	DB22	DB21	DB20	DB19	DB18	DB17	DB16	DB15	DB14	DB13	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	DITH1	DITH0	DEN	DV16	DV15	DV14	DV13	DV12	DV11	DV10	DV9	DV8	DV7	DV6	DV5	DV4	DV3	DV2	DV1	DV0	C3(0)	C2(1)	C1(1)

DITH1	DITH0	Dither Magnitude
0	0	15 (default)
0	1	7
1	0	3
1	1	1 (recommended)

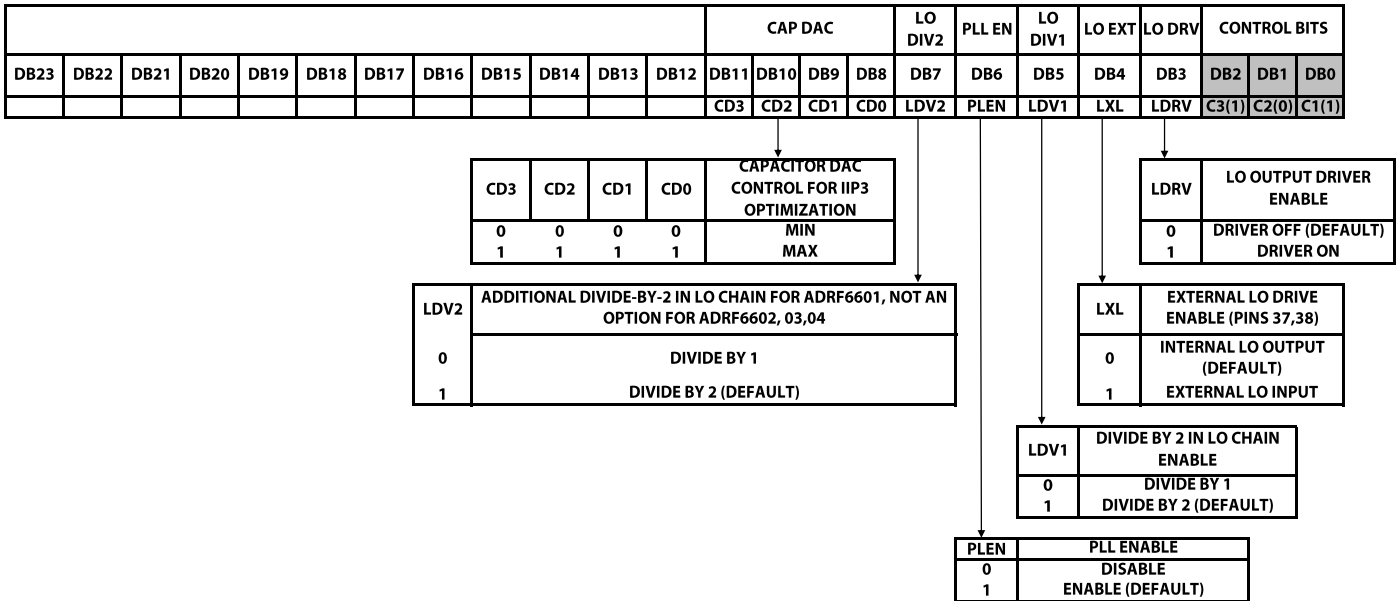
DEN	Dither Enable
0	Disable (recommended)
1	Enable (default)

DV16	DV15	DV14	DV13	DV12	DV11	DV10	DV9	DV8	DV7	DV6	DV5	DV4	DV3	DV2	DV1	DV0	Dither Restart Value
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0x00001 (default)
.
1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0x1FFFF

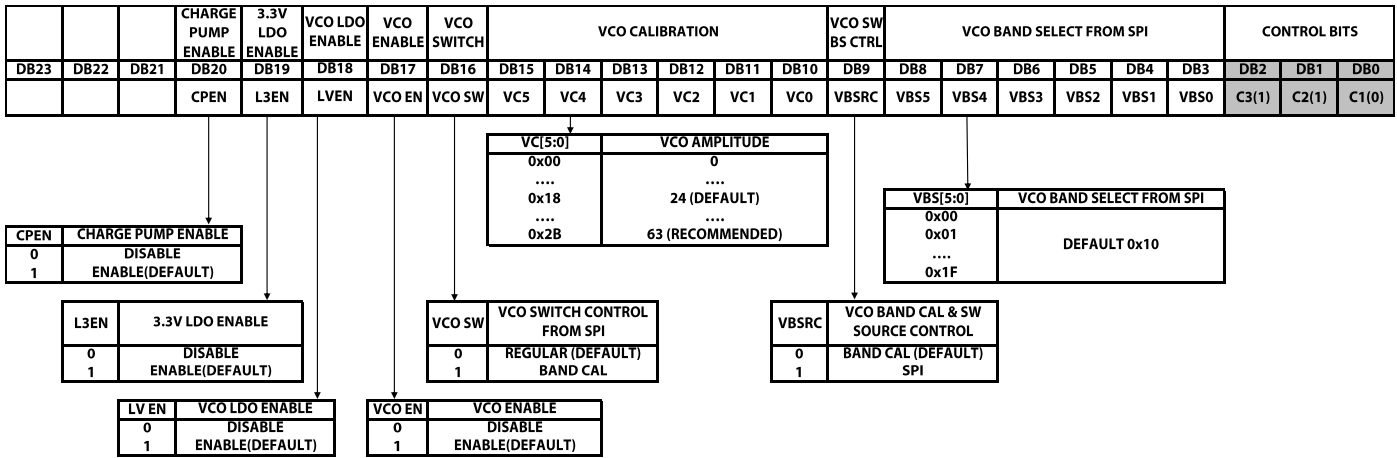
REGISTER 4 – CHARGE PUMP, PFD AND REFERENCE PATH CONTROL (default: 0x0AA7E4)



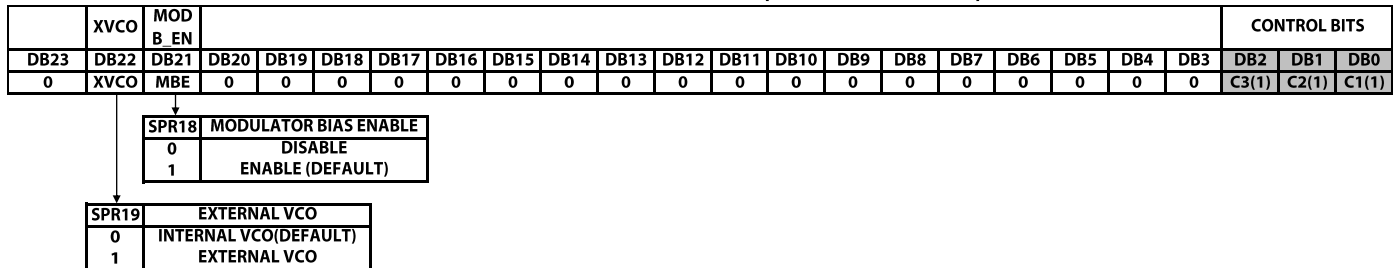
REGISTER 5 – LO PATH AND MODULATOR CONTROL (default: 0x0000E5)



REGISTER 6 VCO CONTROL AND ENABLES (default: 0x1E2106)



REGISTER 7 SPARE REGISTERS (default: 0x000007)



THEORY OF OPERATION

The ADRF6604 integrates a high performance quadrature down converting mixer with a state of the art fractional-N PLL. The PLL also integrates a low noise VCO. The programmable SPI port allows the user to control the fractional-N PLL functions and the modulator optimization functions as well as allowing for an externally applied LO or VCO.

The quadrature modulator core within the ADRF660x family is the next generation of industry leading family of modulators from Analog Devices. The baseband inputs are converted to currents and then mixed to RF using high-performance NPN transistors. The mixer output currents are transformed to a single-ended RF output using an integrated RF transformer balun. The high performance active mixer core, coupled with the low-loss RF transformer balun results in an exceptional OIP3 and OP1dB, with a very low output noise floor for excellent dynamic range. The use of a passive transformer balun rather than an active output stage leads to an improvement in OIP3 with no sacrifice in noise floor. Over the specified frequency range the four devices in the ADRF660x typically provide RF output P1dB of 15dBm, OIP3 of 30dBm, and RF output noise floor of -157dBm/Hz. Typical image rejection under these conditions is 40dB with no additional I and Q gain compensation. Improved performance at specific frequencies can be achieved with the use of the internal CAPDAC, which is programmable via the SPI port, and through the use of a resistor to VCC at the IP3Set pin (pin 29). Adjustment of the CAPDAC allows increments in phase shift at internal nodes in the 660x, thus allowing cancellation of third order distortion with no change in supply current. Connecting a resistor to VCC from the IP3Set pin increases the internal modulator core current, therefore improving overall IP2 and IP3, as well as P1dB. Using the IP3Set pin for this purpose will increase supply current.

The fractional divide function of the PLL allows the frequency multiplication value from REFIN to LO Out to be a fractional value rather than restricted to an integer as in traditional PLLs. In operation, this multiplication value is $INT + (FRAC/MOD)$ where INT is the integer value, FRAC is the fractional value and MOD is the modulus value, all programmable via the SPI port. In previous frac-N PLL designs, the fractional multiplication was achieved by periodically changing the fractional value in a deterministic way. The down side of this was often spurious components close to the fundamental signal. In the ADRF660x family, a sigma-delta modulator is used to distribute the

fractional value randomly, thus significantly reducing the spurious content due to the fractional function.

PROGRAMMING THE ADRF6604

The ADRF6604 is programmed via a three pin SPI port. The description of timing requirements for the SPI port is given in Figure 2. There are eight programmable registers, each with 24 bits, controlling the operation of the device. The register functions can be broken down as follows;

Register 0 – Integer control for the PLL.

Register 1 – Modulus control for PLL.

Register 2 – Fractional control for PLL.

Register 3 – Sigma Delta Function

Register 4 – PLL Charge pump, PFD, reference path control

Register 5 – LO path and modulator control

Register 6 – VCO controls and VCO enable functions

Register 7 – Modulator bias enable, external VCO enable

Note - The PLL has internal calibration that must be run when the ADRF660x is initialized at a given frequency. This calibration is automatically run whenever registers 0, 1, or 2 are programmed. Because the other registers affect PLL performance, the lower three registers should always be programmed last, preferably in the order 0 – 1- 2.

Software is available on the Analog Devices website (www.analog.com) that allows easy programming from a PC running Windows XP™.

LO SELECTION LOGIC

The down converting modulator in the ADRF660x can be used without the internal PLL by applying an external differential LO to pins 37 and 38 (LOP and LON). In addition, when using an LO generated by the internal PLL, the LO signal can be accessed directly at these same pins. This function can be used for debugging purposes or the internally generated LO can be used as the LO for a separate mixer. The operation of the LO generation and whether LOP and LON are input or output is determined by logic levels applied at pin 16 (PLL_EN) and pin 36 (LODRV_EN) as well as bits 3 (LDRV) and 6 (PLEN) in register 5. The combination of externally applied logic and internal bits required for particular LO functions is given in Table 7.

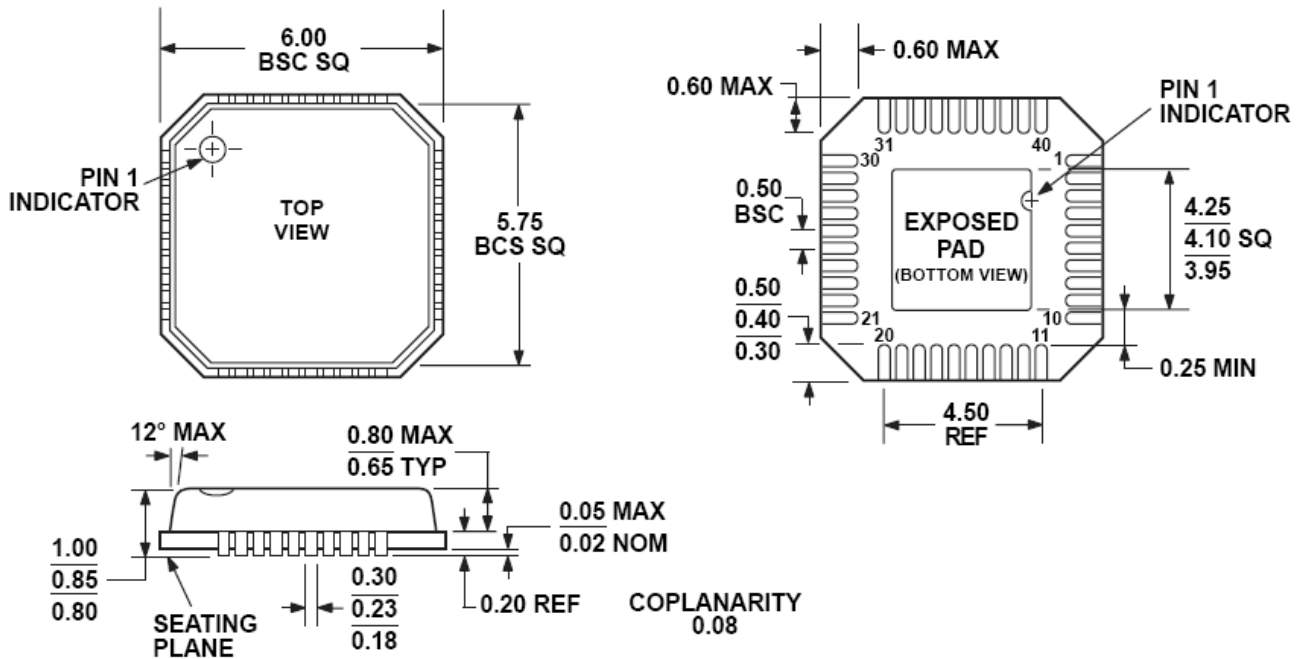
Pins		Register Map		Outputs	
16: PLL_EN	36:LODRV_EN	R5, DB6 PLEN	R5, DB3 LDRV	Output buffer ENB/DSBL	EXT/INT LO
0	X	0	X	DSBL	EXT
0	X	1	X		
1	X	0	X		
1	0	1	0	DSBL	INT
1	X	1	1	ENB	INT
1	1	1	X		

Table 7. LO Selection Logic

OUTLINE DIMENSIONS



40-Lead Lead Frame Chip Scale Package [LFCSP_VQ]
 6 x 6 mm Body, Very Thin Quad
 (CP-40-1)
 Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-220-VJJD-2

Figure 4. 40-Lead LFCSP with exposed paddle.

TABLE 4. ORDERING GUIDE

Model	Temperature Range (°C)	Package Description	Package Option
ADRF6604ACPZ ¹	-40 to +85		

¹ Z indicates Pb-free